



N-Channel NexFET™ Power MOSFETs

 Check for Samples: **CSD16412Q5A**

FEATURES

- Ultra Low Qg and Qgd
- Low Thermal Resistance
- Avalanche Rated
- Pb Free Terminal Plating
- RoHS Compliant
- Halogen Free
- SON 5mm x 6mm Plastic Package

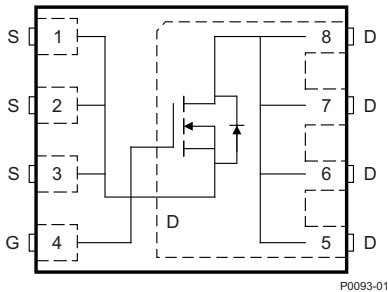
APPLICATIONS

- Point-of-Load Synchronous Buck Converter for Applications in Networking, Telecom and Computing Systems
- Optimized for Control FET Applications

DESCRIPTION

The NexFET™ power MOSFET has been designed to minimize losses in power conversion applications.

Top View



PRODUCT SUMMARY

V_{DS}	Drain to Source Voltage	25	V
Q_g	Gate Charge Total (4.5V)	2.9	nC
Q_{gd}	Gate Charge Gate to Drain	0.7	nC
$R_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 4.5V$	13 mΩ
		$V_{GS} = 10V$	9 mΩ
$V_{GS(th)}$	Threshold Voltage	2	V

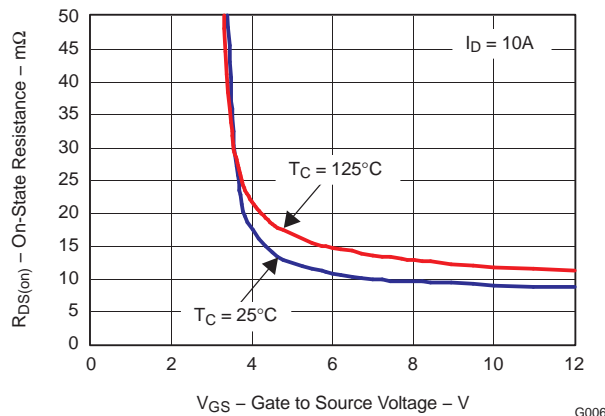
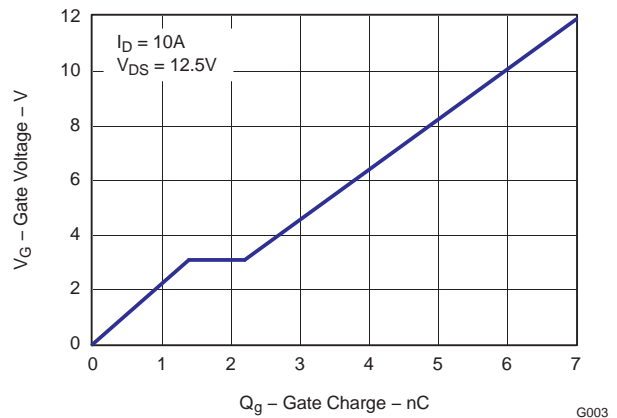
ORDERING INFORMATION

Device	Package	Media	Qty	Ship
CSD16412Q5A	SON 5 × 6 Plastic Package	13-inch reel	2500	Tape and Reel

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ C$ unless otherwise stated		VALUE	UNIT
V_{DS}	Drain to Source Voltage	25	V
V_{GS}	Gate to Source Voltage	+16 / -12	V
I_D	Continuous Drain Current, $T_C = 25^\circ C$	52	A
	Continuous Drain Current ⁽¹⁾	14	A
I_{DM}	Pulsed Drain Current, $T_A = 25^\circ C$ ⁽²⁾	91	A
P_D	Power Dissipation ⁽¹⁾	3	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to 150	°C
E_{AS}	Avalanche Energy, single pulse $I_D = 17A, L = 0.1mH, R_G = 25\Omega$	14	mJ

- (1) $R_{\theta JA} = 42^\circ C/W$ on 1in² Cu (2 oz) on 0.060" thick FR4 PCB.
 (2) Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

 $R_{DS(on)}$ vs V_{GS}

Gate Charge


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ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
Static Characteristics							
B _V DSS	Drain to Source Voltage	V _{GS} = 0V, I _D = 250μA	25			V	
I _{DSS}	Drain to Source Leakage Current	V _{GS} = 0V, V _{DS} = 20V			1	μA	
I _{GSS}	Gate to Source Leakage Current	V _{DS} = 0V, V _{GS} = +16/-12V			100	nA	
V _{GS(th)}	Gate to Source Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1.7	2.0	2.3	V	
R _{DS(on)}	Drain to Source On Resistance	V _{GS} = 4.5V, I _D = 10A		13	16	mΩ	
		V _{GS} = 10V, I _D = 10A		9	11	mΩ	
g _{fs}	Transconductance	V _{DS} = 15V, I _D = 10A		33		S	
Dynamic Characteristics							
C _{ISS}	Input Capacitance	V _{GS} = 0V, V _{DS} = 12.5V, f = 1MHz		410	530	pF	
C _{OSS}	Output Capacitance			350	450	pF	
C _{RSS}	Reverse Transfer Capacitance			32	42	pF	
R _g	Series Gate Resistance	V _{DS} = 12.5V, I _D = 10A		0.7	1.4	Ω	
Q _g	Gate Charge Total (4.5V)			2.9	3.8	nC	
Q _{gd}	Gate Charge Gate to Drain			0.7		nC	
Q _{gs}	Gate Charge Gate to Source			1.4		nC	
Q _{g(th)}	Gate Charge at V _{th}			0.9		nC	
Q _{OSS}	Output Charge		V _{DS} = 13V, V _{GS} = 0V		7		nC
t _{d(on)}	Turn On Delay Time		V _{DS} = 12.5V, V _{GS} = 4.5V, I _D = 10A R _G = 2Ω		5.5		ns
t _r	Rise Time			7.1		ns	
t _{d(off)}	Turn Off Delay Time			5.7		ns	
t _f	Fall Time			3.3		ns	
Diode Characteristics							
V _{SD}	Diode Forward Voltage	I _S = 10A, V _{GS} = 0V		0.85	1.0	V	
Q _{rr}	Reverse Recovery Charge	V _{dd} = 13V, I _F = 10A, di/dt = 300A/μs		12		nC	
t _{rr}	Reverse Recovery Time	V _{dd} = 13V, I _F = 10A, di/dt = 300A/μs		16		ns	

THERMAL CHARACTERISTICS

(T_A = 25°C unless otherwise stated)

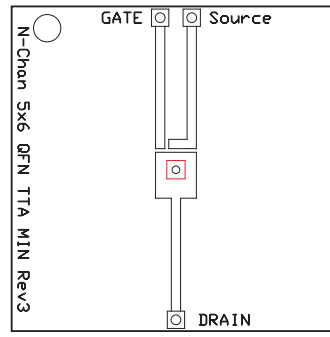
PARAMETER		MIN	TYP	MAX	UNIT
R _{θJC}	Thermal Resistance Junction to Case ⁽¹⁾			3.7	°C/W
R _{θJA}	Thermal Resistance Junction to Ambient ^{(1) (2)}			53	°C/W

- (1) R_{θJC} is determined with the device mounted on a 1 inch square 2 oz. Cu pad on a 1.5 × 1.5 in 0.060 inch thick FR4 board. R_{θJC} is specified by design while R_{θJA} is determined by the user's board design.
- (2) Device mounted on FR4 Material with 1 inch² of 2 oz. Cu.



M0137-01

Max $R_{\theta JA} = 53^{\circ}\text{C/W}$
when mounted on
1 inch² of 2 oz. Cu.

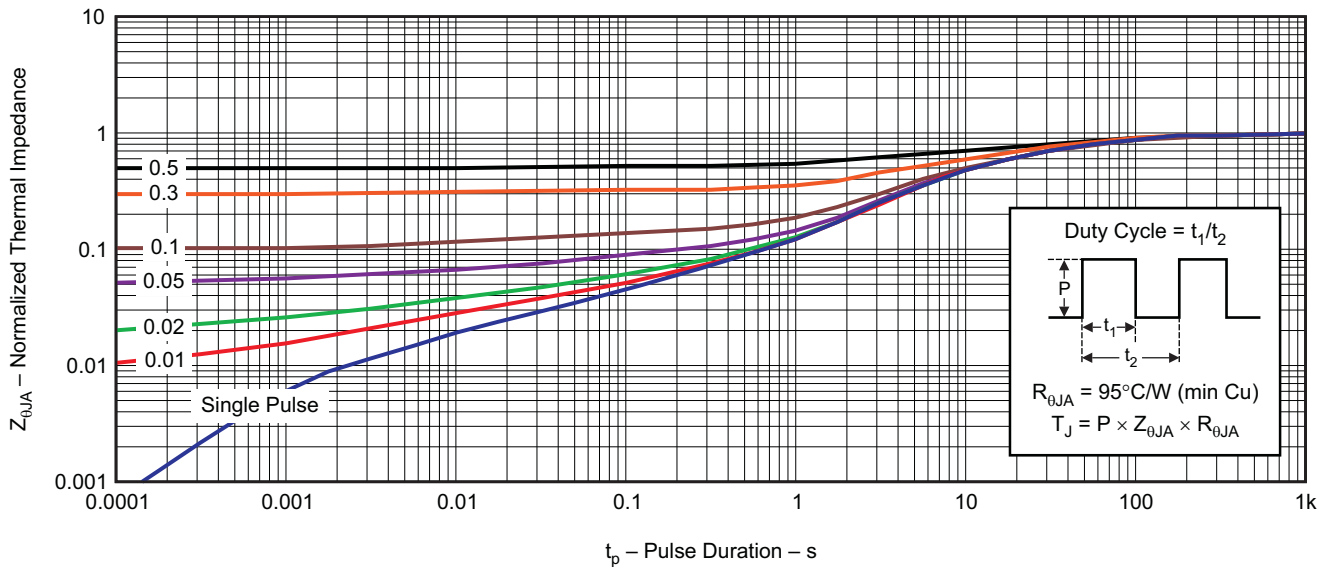


M0137-02

Max $R_{\theta JA} = 119^{\circ}\text{C/W}$
when mounted on
minimum pad area of 2
oz. Cu.

TYPICAL MOSFET CHARACTERISTICS

($T_A = 25^{\circ}\text{C}$ unless otherwise stated)



G012

Figure 1. Transient Thermal Impedance

TYPICAL MOSFET CHARACTERISTICS (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)

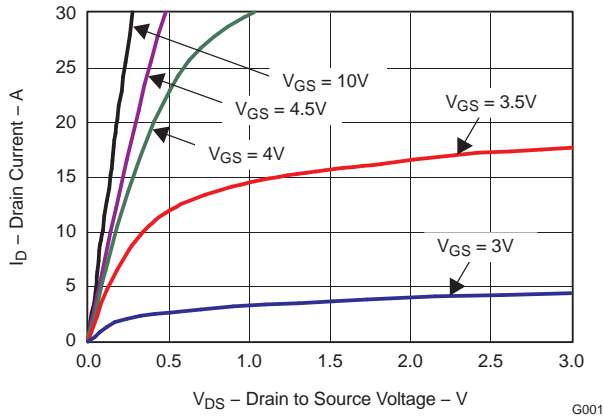


Figure 2. Saturation Characteristics

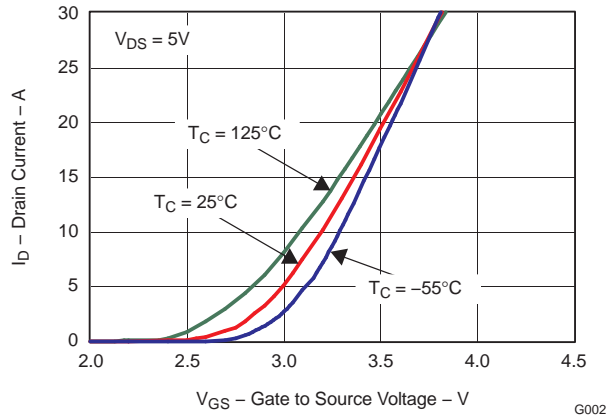


Figure 3. Transfer Characteristics

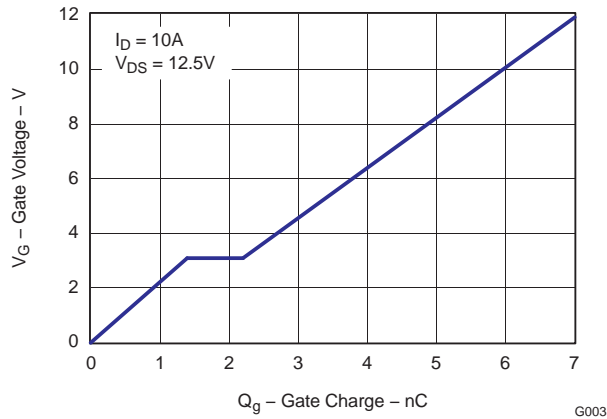


Figure 4. Gate Charge

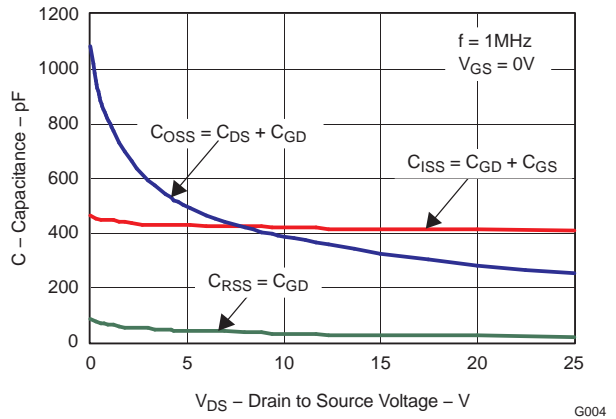


Figure 5. Capacitance

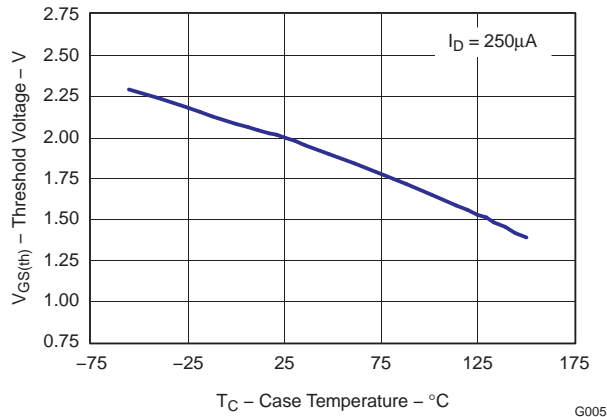


Figure 6. Threshold Voltage vs. Temperature

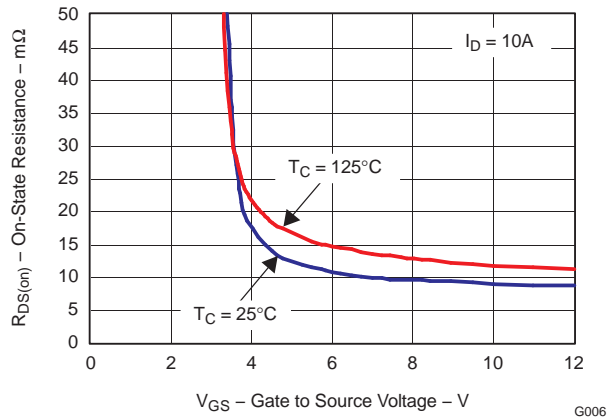


Figure 7. On Resistance vs. Gate Voltage

TYPICAL MOSFET CHARACTERISTICS (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)

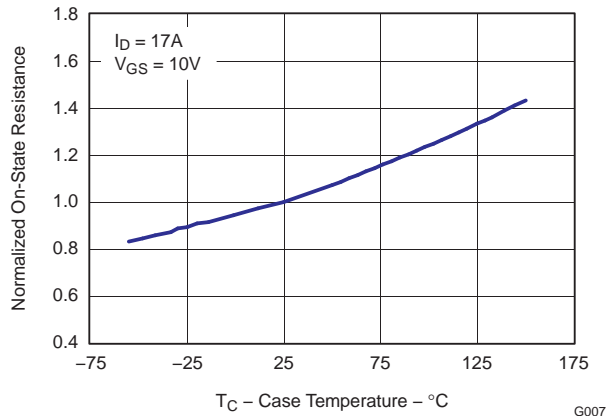


Figure 8. On Resistance vs. Temperature

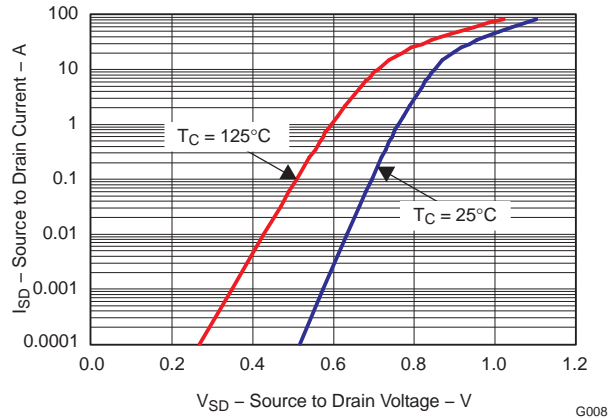


Figure 9. Typical Diode Forward Voltage

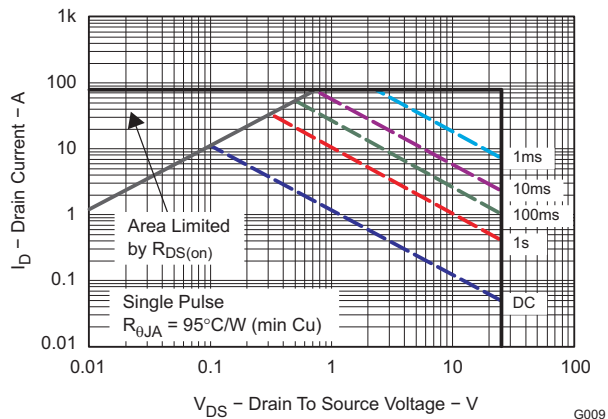


Figure 10. Maximum Safe Operating Area

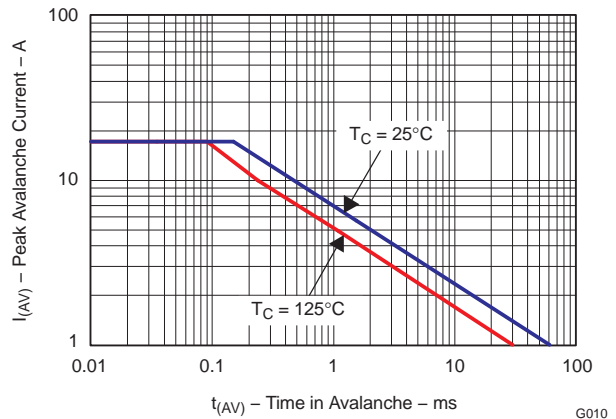


Figure 11. Single Pulse Unclamped Inductive Switching

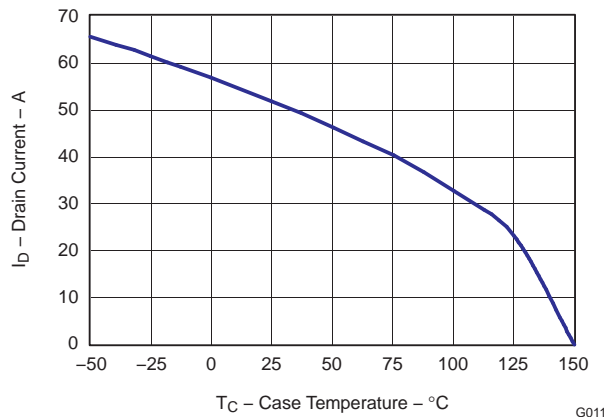


Figure 12. Maximum Drain Current vs. Temperature

MECHANICAL DATA

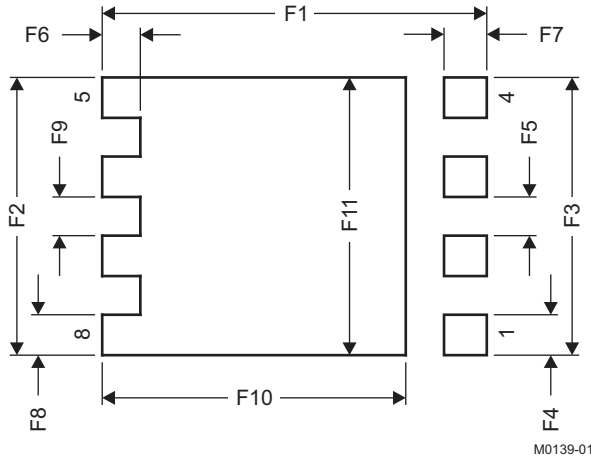
Q5A Package Dimensions



M0135-01

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.33	0.41	0.51
c	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10		
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
theta	0°		12°

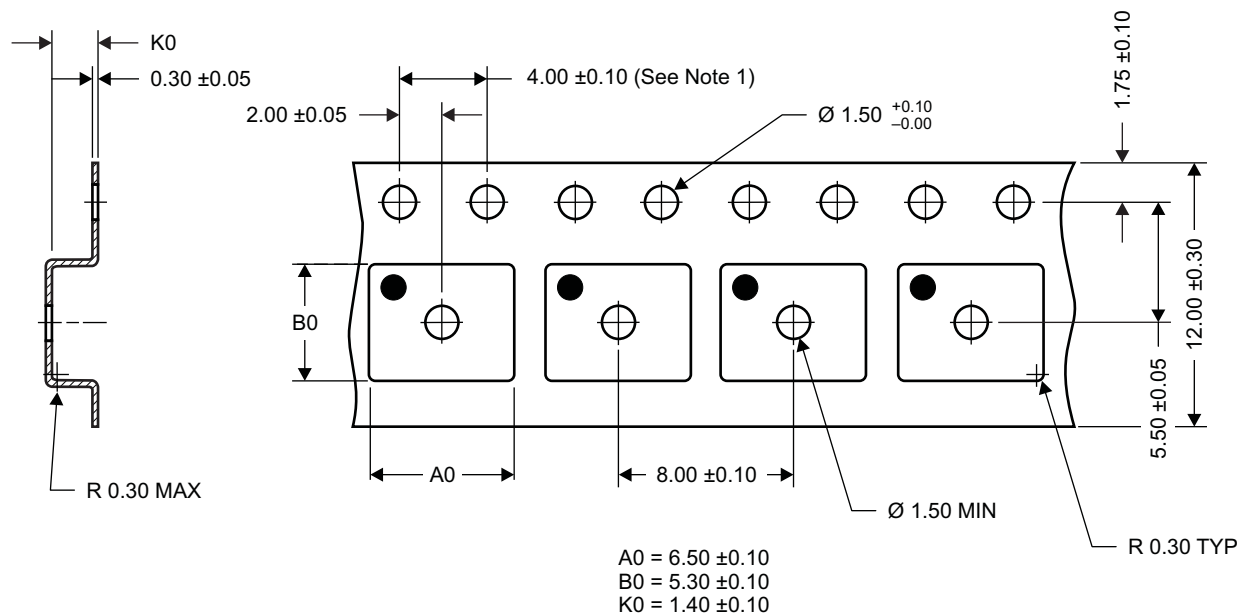
Figure 13. Recommended PCB Pattern



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
F1	6.205	6.305	0.244	0.248
F2	4.46	4.56	0.176	0.18
F3	4.46	4.56	0.176	0.18
F4	0.65	0.7	0.026	0.028
F5	0.62	0.67	0.024	0.026
F6	0.63	0.68	0.025	0.027
F7	0.7	0.8	0.028	0.031
F8	0.65	0.7	0.026	0.028
F9	0.62	0.67	0.024	0.026
F10	4.9	5	0.193	0.197
F11	4.46	4.56	0.176	0.18

For recommended circuit layout for PCB designs, see application note [SLPA005 – Reducing Ringing Through PCB Layout Techniques](#).

Q5A Tape and Reel Information



Notes:

- 10 sprocket hole pitch cumulative tolerance ± 0.2
- Camber not to exceed 1mm IN 100mm, noncumulative over 250mm
- Material: black static dissipative polystyrene
- All dimensions are in mm (unless otherwise specified)
- A0 and B0 measured on a plane 0.3mm above the bottom of the pocket
- MSL1 260°C (IR and Convection) PbF Reflow Compatible

REVISION HISTORY

Changes from Original (August 2009) to Revision A	Page
• Deleted the Package Marking Information section	7

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CSD16412Q5A	SON	DQJ	8	2500	330.0	12.4	6.3	5.3	1.2	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CSD16412Q5A	SON	DQJ	8	2500	340.0	340.0	38.0

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